



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-04
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HWDP*G39B11P	A	Z4XA	2014-07-04
Amount	UoM	Unit type	ST ECOPACK Grade	
320.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte, annealed	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.54,6.10,2.29	2	gull wing	
Comment	Package: DP TO 252 DPAK; MDF valid for STTH506B; STTH506B-TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HWDP*G39B11P					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	3.455	mg	supplier	die	Silicon (Si)	7440-21-3		3.357	mg	971635	10491
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.058	mg	16787	181
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.014	mg	4052	44
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.006	mg	1737	19
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	289	3
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	868	9
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.016	mg	4631	50
Leadframe	Copper & its alloys	155.6	mg	supplier	alloy	Copper(Cu)	7440-50-8		155.32	mg	998201	485375
Leadframe				supplier	alloy	Iron(Fe)	7439-89-6		0.233	mg	1497	728
Leadframe				supplier	alloy	Phosphorus(P)	12185-10-3		0.047	mg	302	147
Die attach	Solder	0.909	mg	supplier	Soft solder	Silver(Ag)	7440-22-4		0.023	mg	25303	72
Die attach				supplier	Soft solder	Lead(Pb)	7439-92-1	7a-Lead in high me	0.868	mg	954895	2713
Die attach				supplier	Soft solder	Tin(Sn)	7440-31-5		0.018	mg	19802	56
Bonding wire	Other inorganic materials	0.662	mg	supplier	bonding wire	Aluminium (Al)	7429-90-5		0.662	mg	1000000	2069
Encapsulation	Other Organic Materials	158.123	mg	supplier	mold compound	Fused Silica	60676-86-0		142.31	mg	899996	444719
Encapsulation				supplier	mold compound	Epoxy Resin	proprietary		11.069	mg	70002	34591
Encapsulation				supplier	mold compound	Phenolic resin	proprietary		3.637	mg	23001	11366
Encapsulation				supplier	mold compound	mixed siloxanes	proprietary		0.791	mg	5002	2472
Encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.316	mg	1998	988
Finishing	Solder	1.251	mg	supplier	Connection coating	Tin(Sn)	7440-31-5		1.251	mg	1000000	3909